

# VA Application Note No. V- 27

**Title:** Copper in nickel sulphate bath containing surfactants

**Summary:** Determination of Cu after UV digestion in nickel sulphate bath containing surfactants

**Sample:** Nickel sulphate plating bath  
**Sample Preparation:** UV digestion

**Copper:** A defined quantity of the Ni bath is mixed with an amount of EDTA which is equivalent to the content of Ni. The pH value is adjusted to 4.6.

**Electrolyte:** EDTA , NH<sub>4</sub>Ac  
**AE:** Pt  
**RE:** Ag/AgCl/KCl 3M  
**Parameters:** DPASV (+50 mV), HMDE  
 $U_{meas} = -500 \text{ mV (2s)}$ ,  $U_{start} = -500 \text{ mV}$ ,  $U_{end} = 0 \text{ mV}$   
 $E_p(\text{Cu}) = -120 \text{ mV}$

<b>Results:</b>	<b>Cu</b> mg/L
	<b>1.1</b>

## Determination of copper

